

# International IR Rectifier

INSULATED GATE BIPOLAR TRANSISTOR

PD-95765

## IRG4BH20K-LPbF

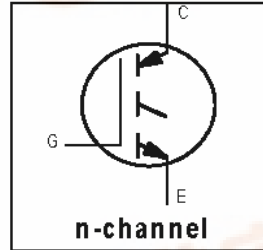
Short Circuit Rated  
UltraFast IGBT

### Features

- High short circuit rating optimized for motor control,  $t_{sc} = 10\mu s$ ,  $V_{CC} = 720V$ ,  $T_J = 125^\circ C$ ,  $V_{GE} = 15V$
- Combines low conduction losses with high switching speed
- Latest generation design provides tighter parameter distribution and higher efficiency than previous generations
- Industry standard TO-262 package
- Lead-Free

### Benefits

- As a Freewheeling Diode we recommend our HEXFRED™ ultrafast, ultrasoft recovery diodes for minimum EMI / Noise and switching losses in the Diode and IGBT
- Latest generation 4 IGBT's offer highest power density motor controls possible



$V_{CES} = 1200V$
$V_{CE(on) typ.} = 3.17V$
@ $V_{GE} = 15V, I_C = 5.0A$



### Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	1200	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	11	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	5.0	
$I_{CM}$	Pulsed Collector Current ①	22	A
$I_{LM}$	Clamped Inductive Load Current ②	22	
$t_{sc}$	Short Circuit Withstand Time	10	$\mu s$
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	V
$E_{ARV}$	Reverse Voltage Avalanche Energy ③	130	mJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	60	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	24	
$T_J$	Operating Junction and	-55 to +150	$^\circ C$
$T_{STG}$	Storage Temperature Range		

### Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	2.1	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	40	
$Wt$	Weight	6 (0.21)	—	g (oz)



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## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	$V_{GE} = 0V, I_C = 250\mu\text{A}$
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	18	—	—	V	$V_{GE} = 0V, I_C = 1.0A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	1.13	—	V/°C	$V_{GE} = 0V, I_C = 2.5mA$
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	3.17	4.3	V	$I_C = 5.0A, V_{GE} = 15V$ See Fig.2, 5
		—	4.04	—		
		—	2.84	—		
$V_{GE(th)}$	Gate Threshold Voltage	3.5	—	6.5		$V_{CE} = V_{GE}, I_C = 250\mu\text{A}$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-10	—	mV/°C	$V_{CE} = V_{GE}, I_C = 1mA$
$g_{fe}$	Forward Transconductance ⑤	2.3	3.5	—	S	$V_{CE} = 100V, I_C = 5.0A$
$I_{CES}$	Zero Gate Voltage Collector Current	—	—	250	$\mu\text{A}$	$V_{GE} = 0V, V_{CE} = 1200V$
		—	—	2.0		$V_{GE} = 0V, V_{CE} = 10V, T_J = 25^\circ\text{C}$
		—	—	1000		$V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$
$I_{GES}$	Gate-to-Emitter Leakage Current	—	—	$\pm 100$	nA	$V_{GE} = \pm 20V$

## Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_g$	Total Gate Charge (turn-on)	—	28	43		$I_C = 5.0A$
$Q_{ge}$	Gate - Emitter Charge (turn-on)	—	4.4	6.6	nC	$V_{CC} = 400V$ See Fig.8
$Q_{gc}$	Gate - Collector Charge (turn-on)	—	12	18		$V_{GE} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	23	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 5.0A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 50\Omega$
$t_r$	Rise Time	—	26	—		
$t_{d(off)}$	Turn-Off Delay Time	—	93	140		
$t_f$	Fall Time	—	270	400		
$E_{on}$	Turn-On Switching Loss	—	0.45	—	mJ	Energy losses include "tail" See Fig. 9,10,14
$E_{off}$	Turn-Off Switching Loss	—	0.44	—		
$E_{ts}$	Total Switching Loss	—	0.89	1.2		
$t_{sc}$	Short Circuit Withstand Time	10	—	—	$\mu\text{s}$	$V_{CC} = 720V, T_J = 125^\circ\text{C}$ $V_{GE} = 15V, R_G = 50\Omega$
$t_{d(on)}$	Turn-On Delay Time	—	23	—	ns	$T_J = 150^\circ\text{C},$ $I_C = 5.0A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 50\Omega$
$t_r$	Rise Time	—	28	—		
$t_{d(off)}$	Turn-Off Delay Time	—	100	—		
$t_f$	Fall Time	—	620	—		
$E_{ts}$	Total Switching Loss	—	1.7	—	mJ	See Fig. 10,11,14
$L_E$	Internal Emitter Inductance	—	7.5	—	nH	Measured 5mm from package
$C_{ies}$	Input Capacitance	—	435	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ See Fig. 7 $f = 1.0MHz$
$C_{oes}$	Output Capacitance	—	44	—		
$C_{res}$	Reverse Transfer Capacitance	—	8.3	—		

### Notes:

① Repetitive rating;  $V_{GE} = 20V$ , pulse width limited by max. junction temperature. ( See fig. 13b )

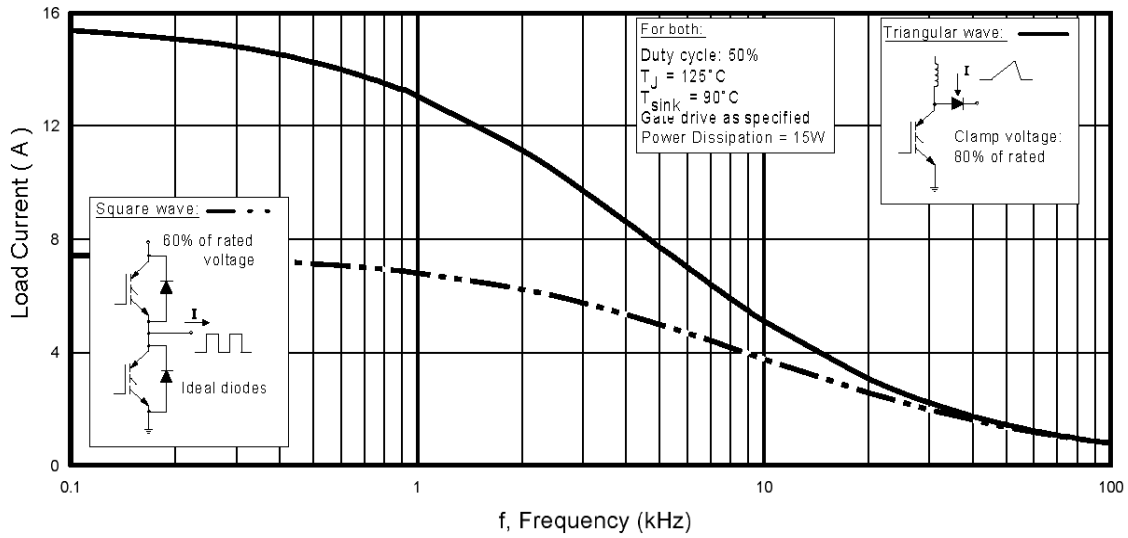
②  $V_{CC} = 80\%(V_{CES}), V_{GE} = 20V, L = 10\mu\text{H}, R_G = 50\Omega$ , (See fig. 13a)

③ Repetitive rating; pulse width limited by maximum junction temperature.

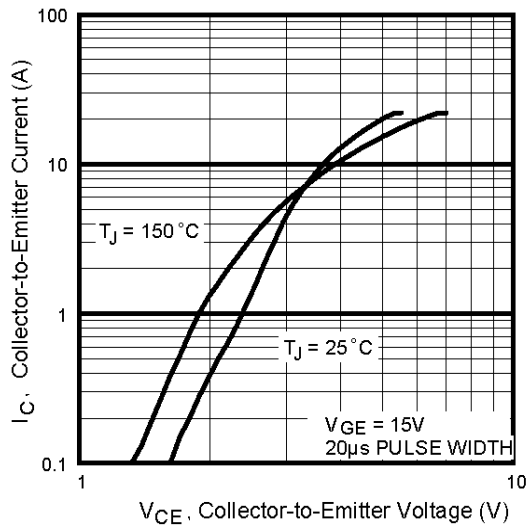
④ Pulse width  $\leq 80\mu\text{s}$ ; duty factor  $\leq 0.1\%$ .

⑤ Pulse width  $5.0\mu\text{s}$ , single shot.

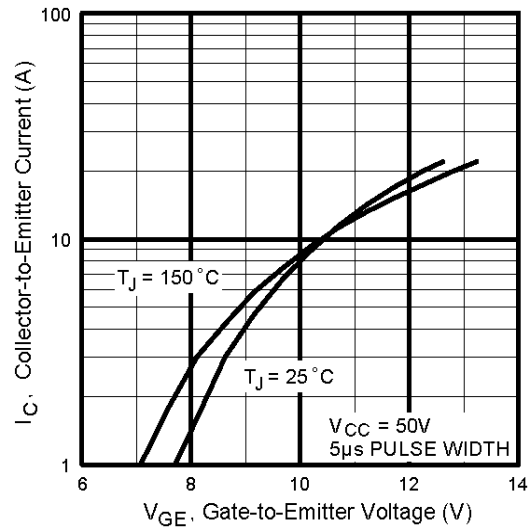
\* When mounted on 1" square PCB (FR-4 or G-10 Material ). For recommended footprint and soldering techniques refer to application note #AN-994.



**Fig. 1** - Typical Load Current vs. Frequency  
(Load Current =  $I_{\text{RMS}}$  of fundamental)



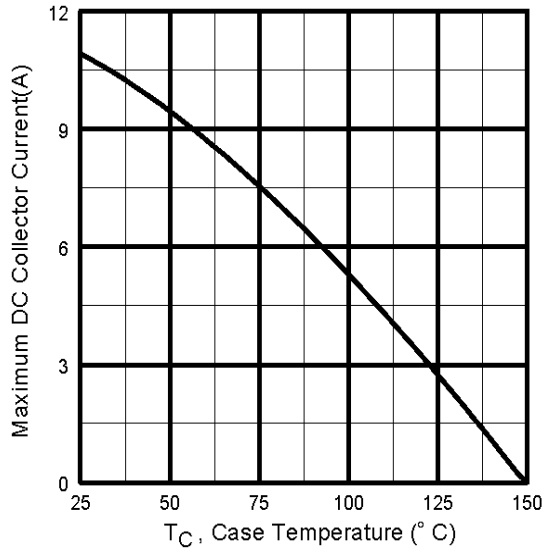
**Fig. 2** - Typical Output Characteristics  
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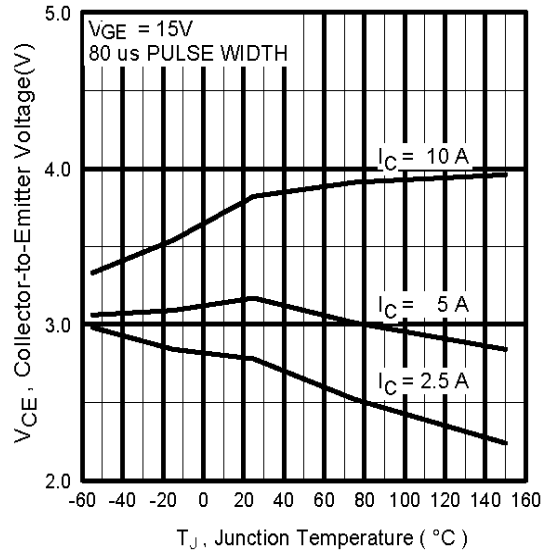
**Fig. 3** - Typical Transfer Characteristics

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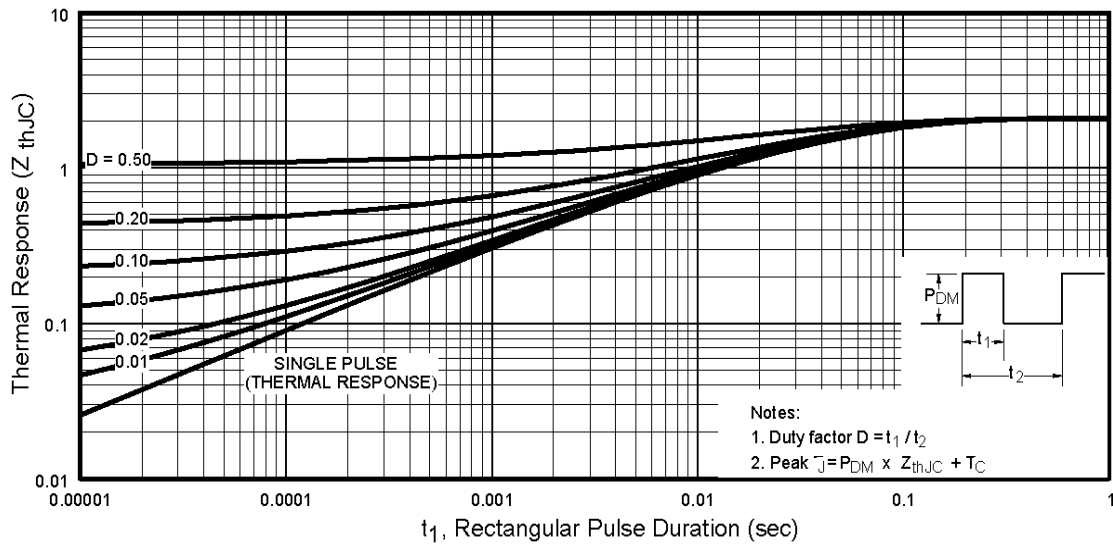
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**Fig. 4** - Maximum Collector Current vs. Case Temperature

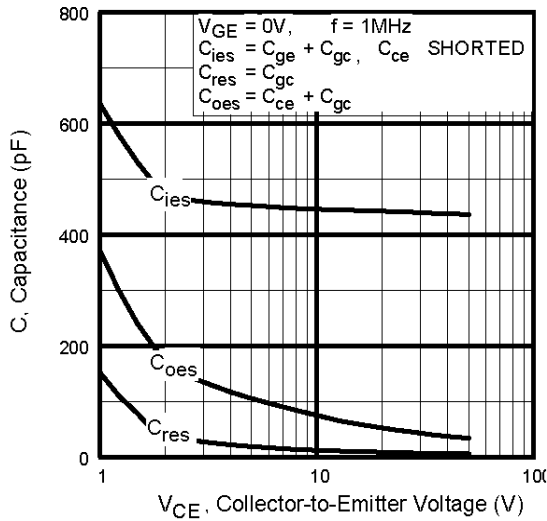


**Fig. 5** - Typical Collector-to-Emitter Voltage vs. Junction Temperature

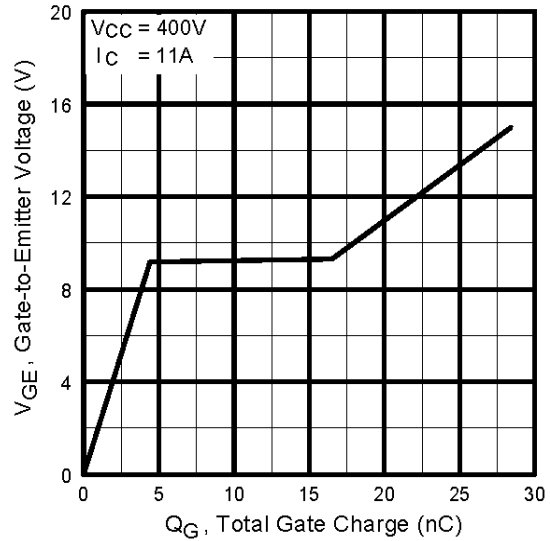


**Fig. 6** - Maximum Effective Transient Thermal Impedance, Junction-to-Case

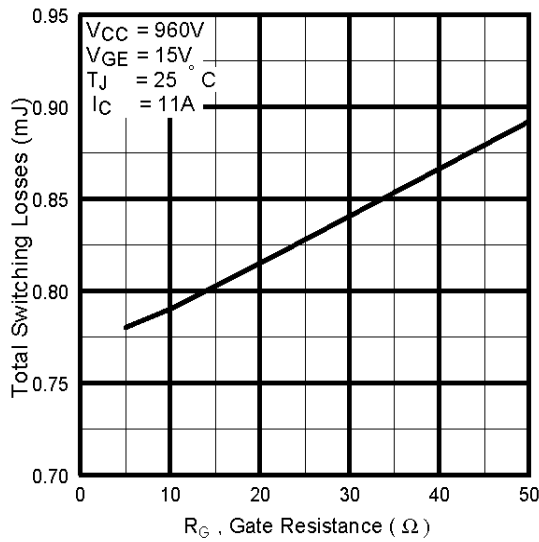
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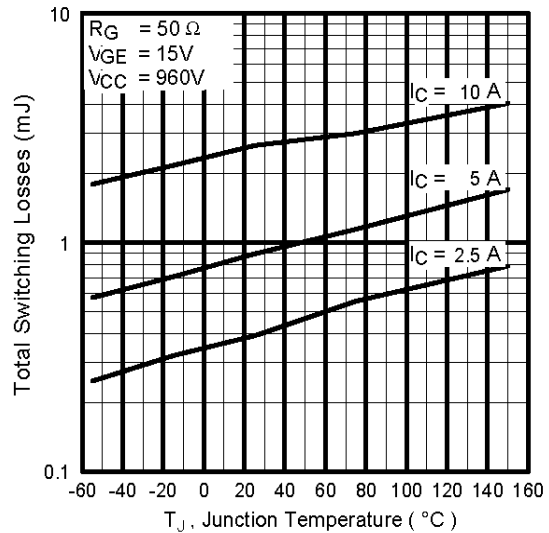
**Fig. 7** - Typical Capacitance vs. Collector-to-Emitter Voltage



**Fig. 8** - Typical Gate Charge vs. Gate-to-Emitter Voltage



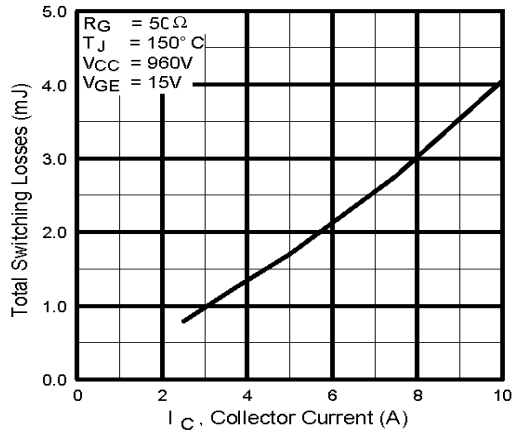
**Fig. 9** - Typical Switching Losses vs. Gate Resistance



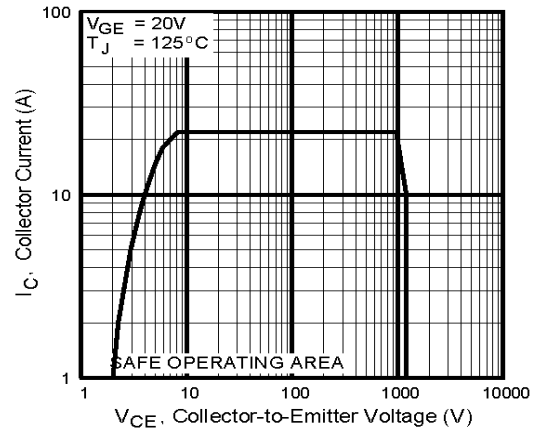
**Fig. 10** - Typical Switching Losses vs. Junction Temperature

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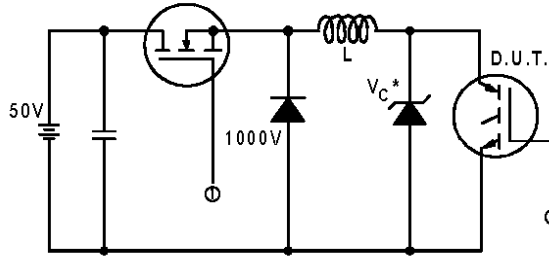
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**Fig. 11** - Typical Switching Losses vs. Collector-to-Emitter Current

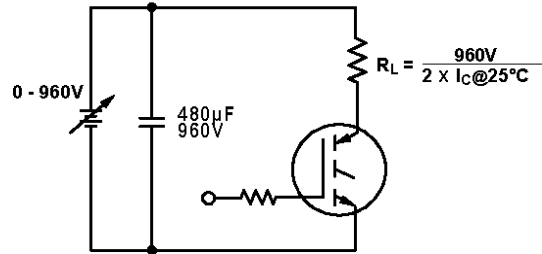


**Fig. 12** - Turn-Off SOA

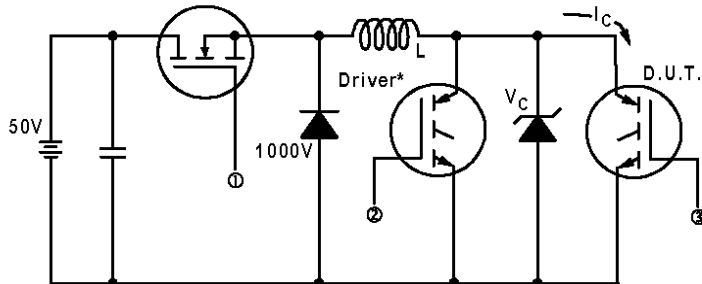


\* Driver same type as D.U.T.;  $V_c = 80\%$  of  $V_{c(max)}$   
 \* Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated  $I_d$ .

**Fig. 13a** - Clamped Inductive Load Test Circuit

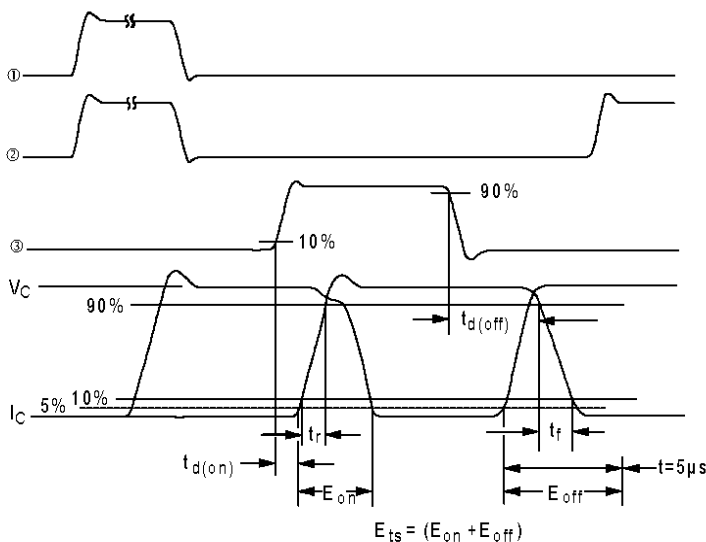


**Fig. 13b** - Pulsed Collector Current Test Circuit



**Fig. 14a** - Switching Loss Test Circuit

\* Driver same type as D.U.T.,  $V_C = 960V$



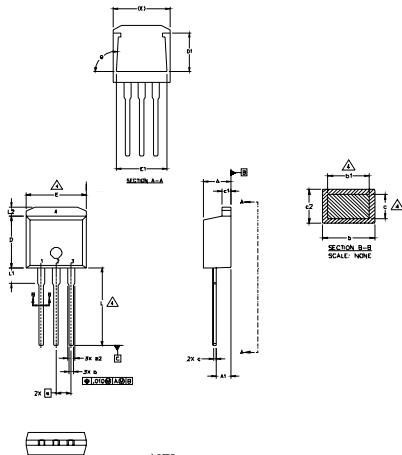
**Fig. 14b** - Switching Loss Waveforms

# IRG4BH20K-LPbF

## TO-262 Package Outline

Dimensions are shown in millimeters (inches)

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### LEAD ASSIGNMENTS

#### HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

#### IGBT

- 1 - GATE
- 2 - COLLECTOR
- 3 - EMITTER

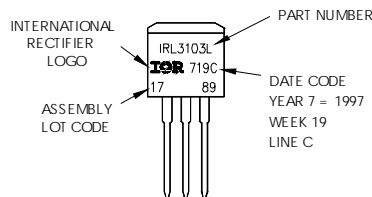
- NOTES
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES]
  3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH; MOLD FLASH SHALL NOT EXCEED 0.127 [0.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY
  - △ DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
  5. CONTROLLING DIMENSION: INCH.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	2.03	2.92	.080	.115	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.40	.045	.055	
c	0.38	0.63	.015	.025	4
c1	1.14	1.40	.045	.055	
c2	0.43	.063	.017	.029	
D	8.51	9.65	.335	.380	3
D1	5.33		.210		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
L	13.46	14.09	.530	.555	
L1	3.56	3.71	.140	.146	
L2		1.65		.065	

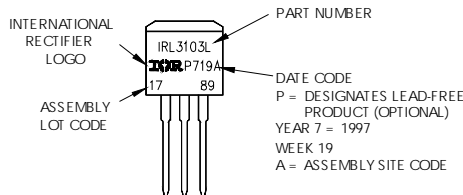
## TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L  
 LOT CODE 1789  
 ASSEMBLED ON WW19, 1997  
 IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position indicates "Lead-Free"



OR



Data and specifications subject to change without notice.

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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
 TAC Fax: (310) 252-7903

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